



# CHT-PLUTO-B1230 Preliminary Datasheet

## High Temperature 1200V/30A Dual SiC MOSFET Module

Version: 1.1

### General description

CHT-PLUTO-B1230 is a high temperature 1200V/30A Dual Silicon Carbide MOSFET in a single hermetic module. It is suitable to implement a power half bridge for applications such as DC-DC converters or motor drives in high temperature environments. The two independent switches can be used in parallel to deliver a total of 60A. This product is guaranteed for normal operation on the full range -55°C to +210°C (T<sub>j</sub>). Each MOSFET has a breakdown voltage in excess of 1200V and is capable of switching current up to 30A. They have a on-resistance of 45mΩ at 25°C and 100mΩ at 210°C at V<sub>GS</sub>=20V. Each MOSFET has an intrinsic body diode.

### Benefits

- High power density converters (support of high-frequency switching and reduced cooling)
- Extended lifetime and high reliability
- Harsh environments and high temperature power converters
- Seamless driving with HADES® gate driver solutions

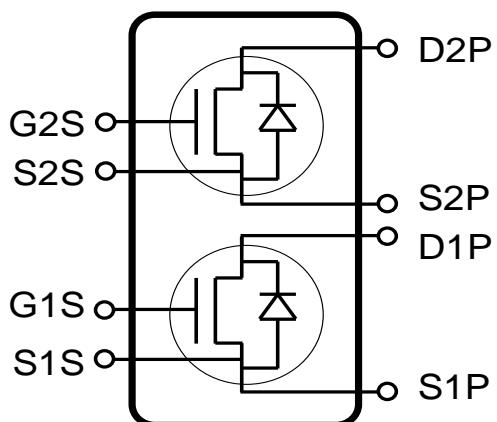
### Applications

- DC motor drives and actuator control
- DC-DC converters

### Features (per switch)

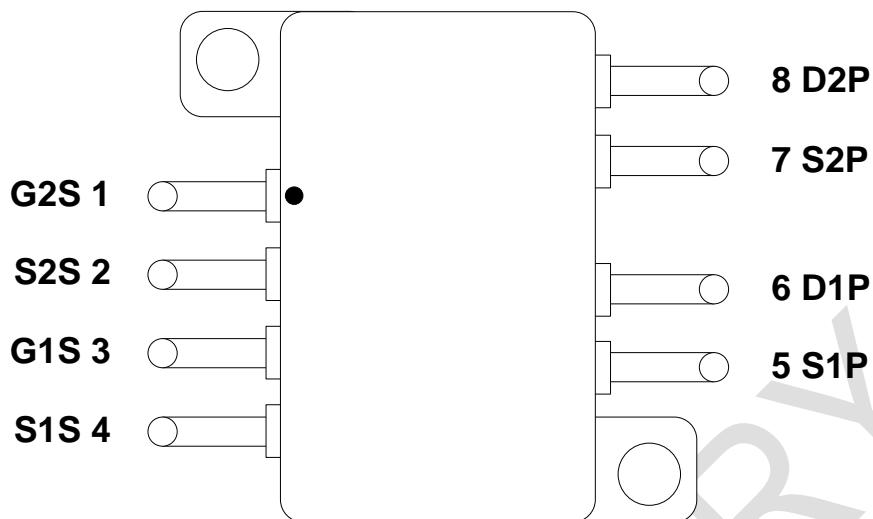
- Specified from -55 to +210°C (T<sub>j</sub>)
- V<sub>DS</sub> Max: 1200V
- Max Continuous Current:
  - 30A @ T<sub>c</sub>≤160°C
  - 25A @ T<sub>c</sub>=175°C
- Max Pulsed Current: 40A
- Typical On-resistance:
  - R<sub>DSon</sub>= 20 mΩ @ T<sub>j</sub>=25°C
  - R<sub>DSon</sub>= 60 mΩ @ T<sub>j</sub>=210°C
- High Speed Switching
- Voltage control: V<sub>GS</sub>=-5V/20V
- Low gate charge: Q<sub>GS</sub>: 44nC
- Hermetic package with isolated case

### Functional Block Diagram



Note: the schematic shows the intrinsic body diode

## Package configuration and Pin Description



Pin ID	Pin Name	Pin Description	Pin Finish
1	G2S	Gate of MOSFET 2 (Signal Pin)	Nickel
2	S2S	Source of MOSFET 2 (Signal Pin)	Nickel
3	G1S	Gate of MOSFET 1 (Signal Pin)	Nickel
4	S1S	Source of MOSFET 1 (Signal Pin)	Nickel
5	S1P	Source of MOSFET 1 (Power Pin)	Nickel
6	D1P	Drain of MOSFET 1 (Power Pin)	Gold
7	S2P	Source of MOSFET 2 (Power Pin)	Nickel
8	D2P	Drain of MOSFET 2 (Power Pin)	Gold
	Body	Package body (isolated from Pins)	Nickel

**Absolute Maximum Ratings**

Gate-to-Source voltage $V_{GS}$	-5V to 22V
Drain-to-Source voltage $V_{DS}$	1200V
Max DC Drain current $I_{DS}$	30A
Max Junction temperature $T_{jmax}$	210°C
Power dissipation at $T_c=175^\circ\text{C}$ (*)	66W

**ESD Rating**

Human Body Model	>1kV
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**Operating Conditions (per switch)**

Gate-to-Source voltage $V_{GS}$	-5V to 20V
Drain-to-Source voltage $V_{DS}$	- 1200V
Max DC drain current $I_{DS}$ ( $T_c=175^\circ\text{C}$ )	25A
Max DC drain current $I_{DS}$ ( $T_c \leq 160^\circ\text{C}$ )	30A
Max pulsed drain current	40A
Junction temperature	-55°C to +210°C

(\*): per switch position and including switching losses

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## Electrical characteristics (per switch)

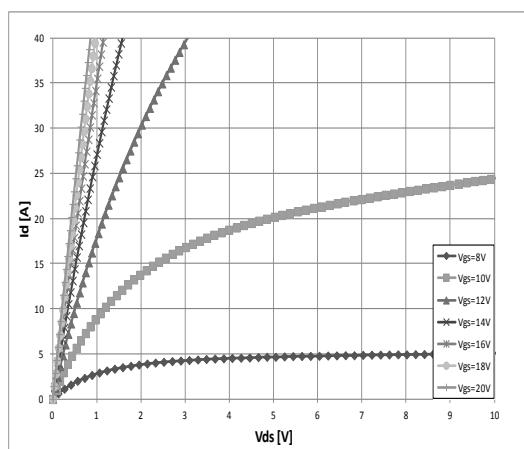
Unless otherwise stated,  $T_j = 25^\circ\text{C}$ . **Bold** figures point out values valid over the whole temperature range ( $T_j = -55^\circ\text{C}$  to  $+210^\circ\text{C}$ ).

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Threshold voltage	$V_{TH}$	$T_j=25^\circ\text{C}; I_D = 1\text{mA}; V_{DS} = 20\text{V}$		4.45		V
		$T_j=210^\circ\text{C}; I_D = 1\text{mA}; V_{DS} = 20\text{V}$		3.82		V
Drain cut-off current	$I_{DSS}$	$V_{GS}=0\text{V}, V_{DS}=1200\text{V}, T_j=25^\circ\text{C}$		80		nA
		$V_{GS}=0\text{V}, V_{DS}=1200\text{V}, T_j=210^\circ\text{C}$		800		μA
Gate leakage current	$I_{GSS}$	$V_{GS}=20\text{V}, V_{DS}=1200\text{V}, T_j=25^\circ\text{C}$		10		nA
		$V_{GS}=20\text{V}, V_{DS}=1200\text{V}, T_j=210^\circ\text{C}$		40		nA
Static drain-to-source resistance	$R_{DSon}$	$V_{GS}=20\text{V}, ID=25\text{A}, T_j=25^\circ\text{C}$		20		mΩ
		$V_{GS}=20\text{V}, ID=25\text{A}, T_j=210^\circ\text{C}$		60		mΩ
Breakdown drain-to-source voltage (DC characterization)	$V_{BRDS}$	$V_{GS}=0\text{V}; ID = 1\text{ mA}$	<b>1200</b>			V
Input capacitance	$C_{ISS}$	$V_{GS}=0\text{V}_{DC}, V_{DS}=600\text{V}$ $f = 1\text{ MHz}$ $V_{AC} = 25\text{mV}$		2674		pF
Output capacitance (includes diode capacitance)	$C_{OSS}$			152		pF
Feedback capacitance	$C_{RSS}$			54		pF
Turn-on delay time	$T_{d(ON)}$	$VDD=600\text{V}; VGS= -4/20\text{V}$ $ID = 30\text{A}$ $RG= 3.3\Omega; L = 856\mu\text{H}$		13		ns
Fall time	$T_r$			24		ns
Turn-off delay time	$T_{d(OFF)}$			40		ns
Rise time	$T_f$			38		ns
Turn-On Switching Loss	$E_{on}$			390		μJ
Turn-Off Switching Loss	$E_{off}$			430		μJ
Internal gate resistance	$R_G$	$V_{GS}=0\text{V}_{DC}, f = 1\text{ MHz};$ $V_{AC} = 25\text{mV}$		2.5		Ω
Gate to Source Charge	$Q_{GS}$	$Tj=25^\circ\text{C} ; VDD= 600\text{V};$ $ID = 20\text{A}; VGS = -4/20\text{V}$		44		nC
Gate to Drain Charge	$Q_{GD}$			82		nC
Total Gate Charge	$Q_G$			214		nC
Diode forward voltage	$V_F$	$Tj=25^\circ\text{C}; IF=30\text{A}$		3.3		V
		$Tj=210^\circ\text{C}; IF=30\text{A}$		3.1		V
Reverse recovery time	$T_{rr}$	$Tj=25^\circ\text{C}; V_{DS}=300\text{V};$ $V_{GS} = -5\text{V};$ $I_F=20\text{A}; dI_F/dt = 100\text{A}/\mu\text{s}$		220		ns
Peak reverse recovery current	$I_{prr}$			2.3		A

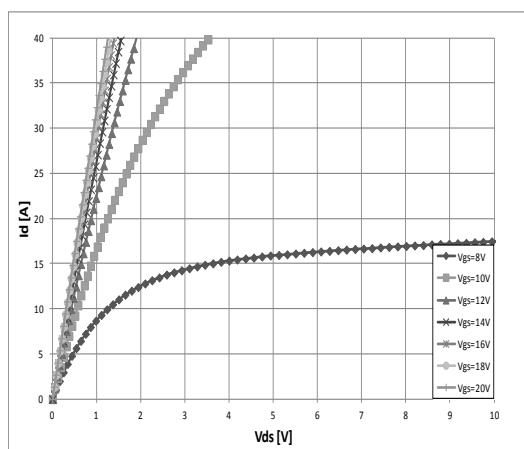
## Thermal Characteristics

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Junction-to-Case Thermal resistance MOSFET	$R_{θJC}$			0.7		°C/W

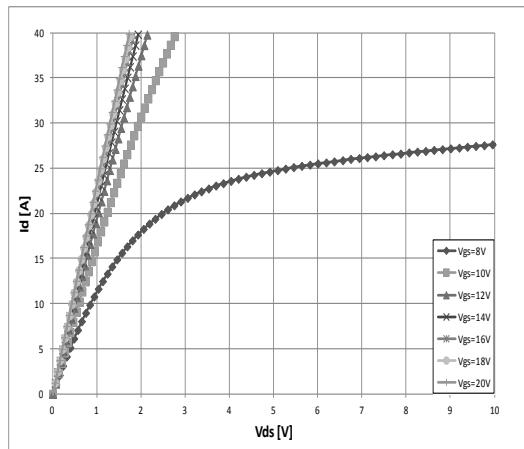
### Typical performances (per switch)



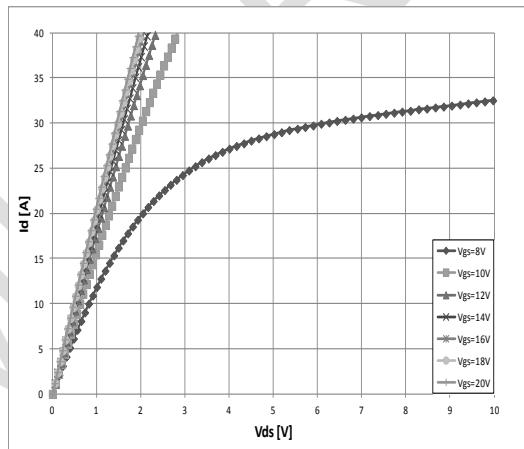
**Figure 1:** Drain current vs  $V_{DS}$  ( $T_j = 25^\circ\text{C}$ )



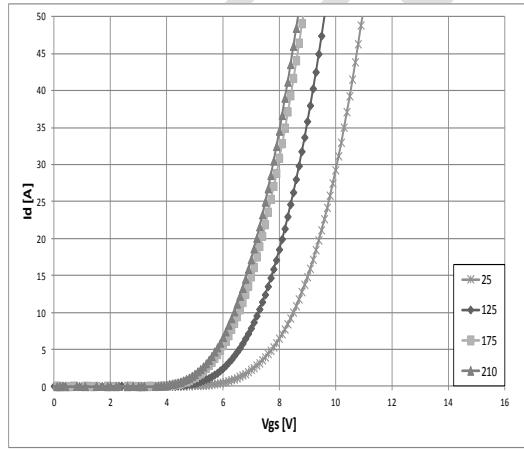
**Figure 2:** Drain current vs  $V_{DS}$  ( $T_j = 125^\circ\text{C}$ )



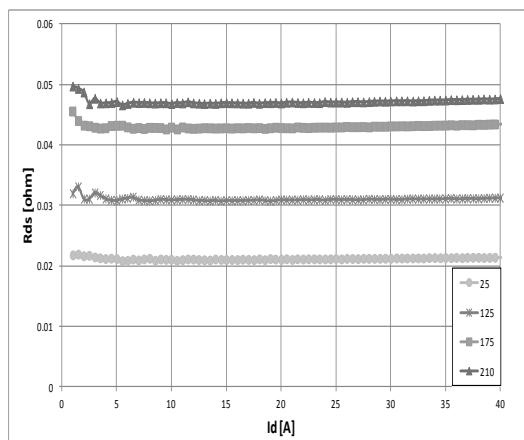
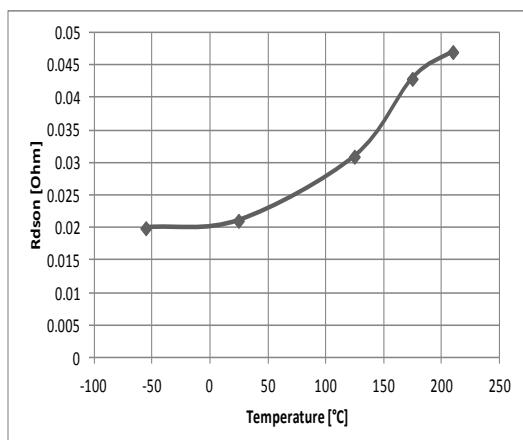
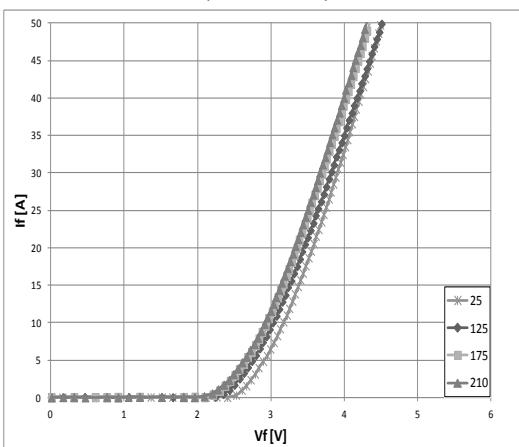
**Figure 3:** Drain current vs  $V_{DS}$  ( $T_j = 175^\circ\text{C}$ )



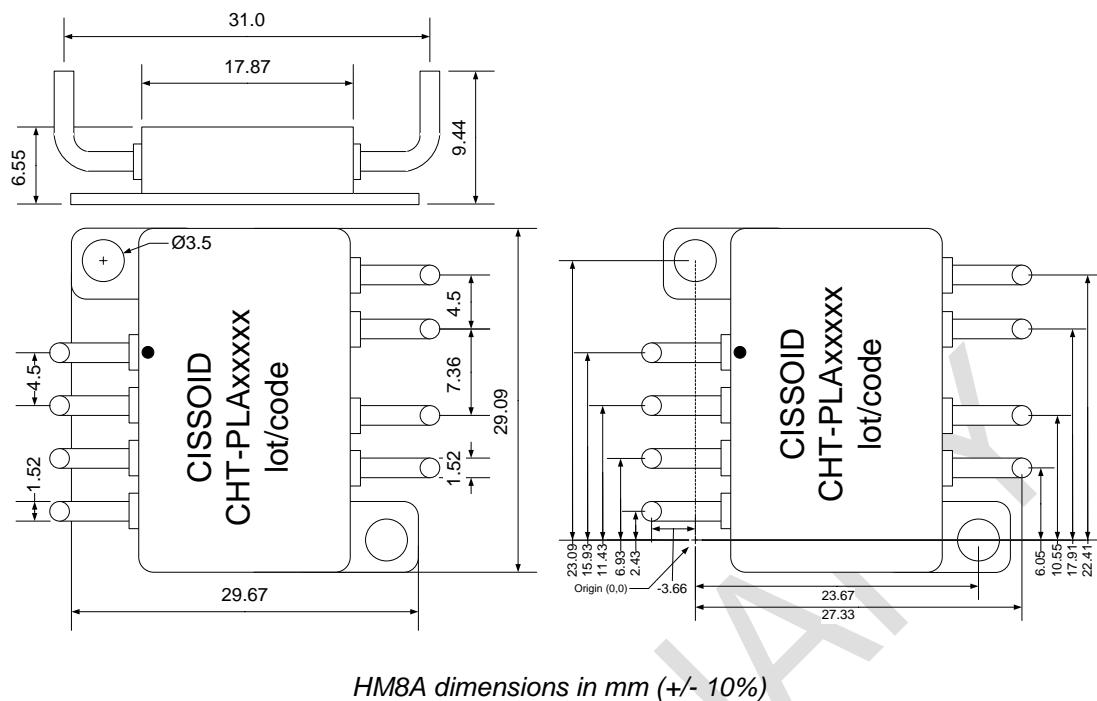
**Figure 4:** Drain current vs  $V_{DS}$  ( $T_j = 210^\circ\text{C}$ )



**Figure 5:** Drain current vs  $V_{GS}$  voltage

**Typical performances (cnt'd)****Figure 6:** On-state drain source resistance vs. Drain current ( $V_{GS} = 20V$ )**Figure 7:** On-state drain source resistance vs. Temperature ( $V_{GS} = 20V$ ;  $I_D = 25A$ )**Figure 8:** Diode  $I_D$  vs  $V_{DS}$  (3<sup>rd</sup> quadrant;  $V_{GS} = -5V$ )

## Package Dimensions



## Ordering Information

Product Name	Ordering Reference	Package	Marking
CHT-PLUTO-B1230	CHT-PLA2316A-HM8A-T	HM8A	CHT-PLA2316A

## Related products

Product Name	Function	Ordering Reference
CHT-PLUTO-B1220	Dual 1200V/20A SiC MOSFET Module	CHT-PLA8294A-HM8A-T
CHT-PLUTO-C1230	1200V/30A SiC Async Buck or Boost Power Module	CHT-PLA2228A-HM8A-T
CHT-PLUTO-C1220	1200V/20A SiC Async Buck or Boost Power Module	CHT-PLA3777A-HM8A-T

## Contact & Ordering

### CISSOID S.A.

<b>Headquarters and contact EMEA:</b>	CISSOID S.A. – Rue Francqui, 3 – 1435 Mont Saint Guibert - Belgium T : +32 10 48 92 10 - F: +32 10 88 98 75 Email: <a href="mailto:sales@cissoid.com">sales@cissoid.com</a>
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